

激光开槽解决方案

高性能Low-k晶圆激光开槽系统

- 可提供皮秒紫外、纳秒紫外设备
- 更高效的光路和激光控制系统
- 新型自动化上下料系统
- 稳定的激光和功率闭环控制系统
- 连续可变点和切割宽度



产品性能效果展示

Nanosecond LG Profile



PicoSecond LG Profile



Bottom U shape

	Nano Laser	Pico Laser
Laser	Power:>11W Frequency: 1-200KHz	Power:>20W Frequency: 1-2000KHz
Cut axis	Up to 1000mm/s	
Accuracy	<±2μm	
Optics	Dual wide laser multi beam Continuous variable beam 10-90um	
Profile	Wide U shape & Flat top shape	
Roughness	Flat ±3um on metal/non-metal	Super flat ±1um on metal/non-metal
Target depth	Typically 8 ~ 18um	Typically 5~ 20um
In-situ monitoring	-Continuous variable width 10-90μm -Laser power compensation -Vision inspection Low/High -Separate cleaning&coating -Pneumatics & motion monitoring	



设备细节配置信息

	LEAD Model: L1-7100/L1-7500	DIXX	DIXX
Laser Head	PS/NS solid	PS Solid	NS Solid
Wavelength	355nm	355nm	355nm
Laser Mode.	Pulse CW	Pulse CW	Pulse CW
Pulse width	ns:80ns-150ns ps:<15ps	<15ps	80ns-150ns
Power Stability	<±3% over ghours	<±3% over ghours	<±3% over 8hours
Polarization Direction	Linear	Linear	Linear
Slot width Control	10-90μm Continuing Adjust	Several Mask Control widths	Several Mask Control widths
Refrigeration Method	Water-Cooling	Water-Cooling	Water-Cooling
Ambient Temperature (°C)	17-30	17-30	17-30
Optical Path Design	Dual Optical Path Design	Dual Optical Path Design	Dual Optical Path Design
Maximum Speed	1000mm/s	1000mm/s	1000mm/s
Positioning Accuracy	<±2μm	<±2μm	<±2μm
Repeatability	<±1μm	<±1μm	<±1μm

激光开槽解决方案

Machine Supplier	Lead	D****	Comparison
Machine Type	L1-7100/L1-7500	XXLXX61	NA
Grooving	Yes	Yes	Comparable
Delivery Time	≤12 weeks	≥24 weeks	Lead
Maintain	7*24 Hrs	NA	Lead
Warranty	≤12000Hrs	≤8000Hrs	Lead
Service	Local Service	Local & Remote mode	Lead
Beam Type	10-90μm	40/50/60μm	Lead

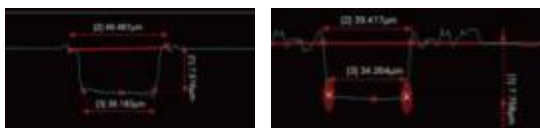
激光全切解决方案

	Nano Grooving + Laser full cut		Pico Grooving + Laser full cut	
Machine lifetime maintenance	Available		Available	
Process	Dual Narrow Dual wide	Dual Narrow Multi Beam Clean Pass	Dual Narrow Multi wide	Dual Narrow Multi Beam Clean Pass
Product thickness(μm)	40~1000	40~250	40~1000	40~100
Street material	Low-k PI TEG(Cu Al etc)	Si, Low-k, PI TEG(Cu Al etc) SiC, GaAs, Ge DAF tape	Low-k PI TEG(Cu Al etc)	Si, Low-k, PI TEG(Cu Al etc) DAF tape

特殊功能

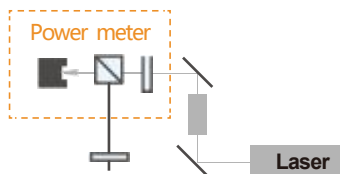
槽型测量

- 在生产过程中测量槽型
- 提前规避工艺风险



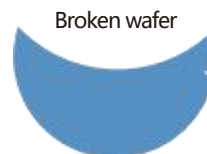
实时功率监控

防止功率突然变化引起的异常情况



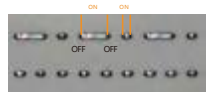
破片切割

- 切割破碎的晶圆
- 开发特殊软件功能



MPW晶圆切割

- 边缘不切功能 (高精度控制激光位置)
- 多尺寸芯片晶圆加工
- 通过偏置芯片增加芯片数量



Increased no. of die

